

#27/GNE  
2/17/02  
Admth

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2827**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro MURATA

Group Art Unit: 2827

Application No.: 09/245,288

Examiner: D. Graybill

Filed: February 5, 1999

Docket No.: 101937

For: SEMICONDUCTOR APPARATUS SUBSTRATE, SEMICONDUCTOR  
APPARATUS, AND METHOD OF MANUFACTURING THEREOF AND  
ELECTRONIC APPARATUS

AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. §1.116

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Further to the October 4 personal interview with Examiner Graybill, and in reply to the Office Action mailed November 27, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 3, 4, 7, 9 and 10 as follows:

1. (Three Times Amended) A substrate for semiconductor apparatus,  
comprising:

a substrate main body having a first surface for mounting the semiconductor device, a second surface and a plurality of through-holes;

a plurality of leads formed on the first surface, the plurality of leads extending from a peripheral area toward a central area of the substrate main body; and